

Ultra-Low Noise, 3A Power Module

Features

- 3A Continuous Operating Current
- Input Voltage Range: 3.0V to 5.5V
- Adjustable Output Voltage Down to 1.0V
- Output Noise Less Than 5 mV
- Ultra-Fast Transient Performance
- Unique Switcher Plus LDO Architecture
- Fully Integrated MOSFET Switches
- Micropower Shutdown
- Easy Upgrade from LDO as Power Dissipation Becomes an Issue
- Thermal Shutdown and Current-Limit Protection
- 4 mm × 6 mm × 1.55 mm LQFN Package

Applications

- Point-of-Load Applications
- Networking, Server, Industrial Power
- Wireless Base Stations
- Sensitive RF Applications

General Description

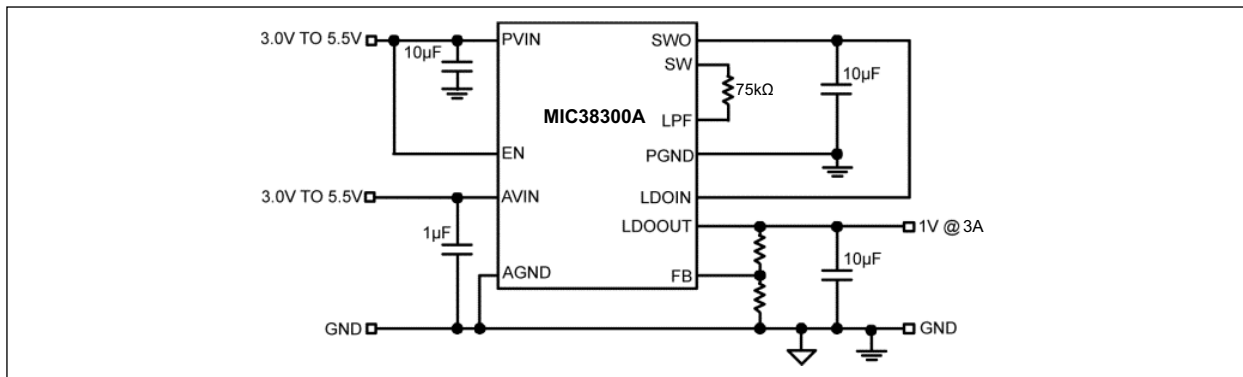
The MIC38300A is a 3A current step-down converter that provides the benefits of an LDO in respect to ease of use, fast transient performance, high PSRR, and low noise while offering the efficiency of a switching regulator.

As output voltages move lower, the output noise and transient response of a switching regulator become an increasing challenge for designers. By combining a switcher whose output is slaved to the input of a high-performance LDO, high efficiency is achieved with a clean low noise output. The MIC38300A is designed to provide less than 5 mV of peak to peak noise and over 70 dB of PSRR at 1 kHz. Furthermore, the architecture of the MIC38300A is optimized for fast load transients that allow maintenance of less than 30 mV of output voltage deviation even during ultra-fast load steps, making the MIC38300A an ideal choice for low-voltage ASICs and other digital ICs.

The MIC38300A features a fully integrated switching regulator and LDO combo, operates with input voltages from 3.0V to 5.5V input, and offers adjustable output voltages down to 1.0V.

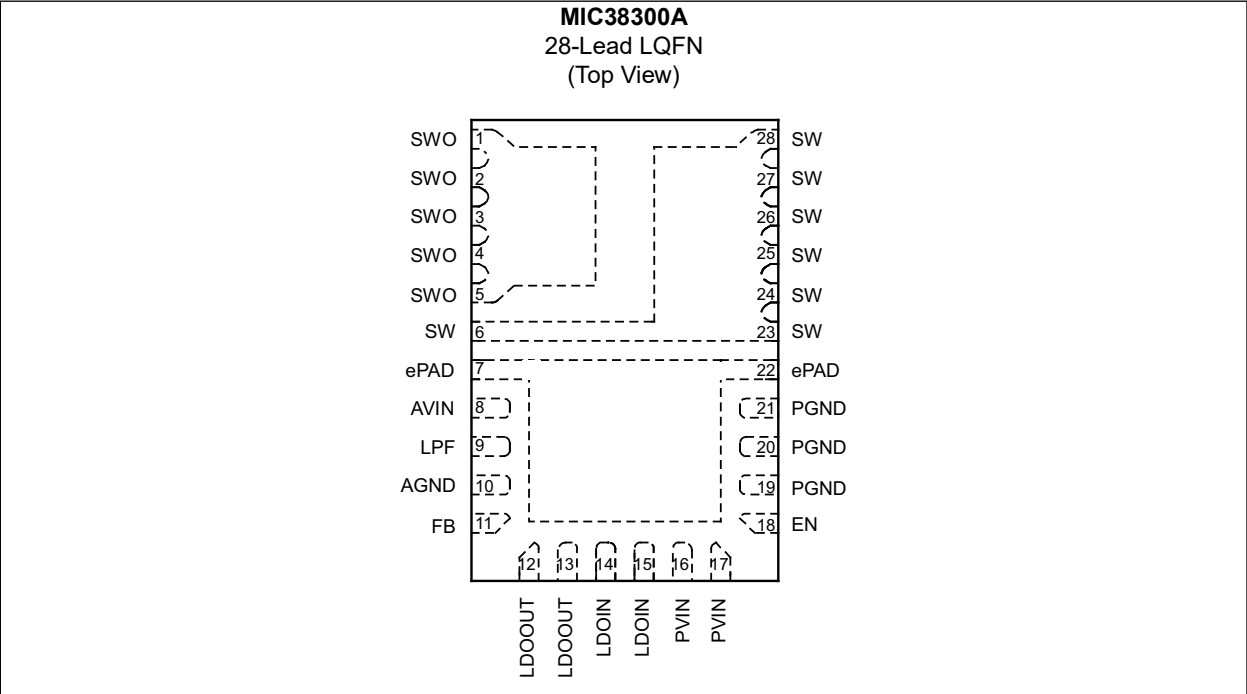
The MIC38300A is offered in the small 28-lead 4 mm × 6 mm × 1.55 mm LQFN package and can operate from -40°C to +125°C.

Typical Application Circuit

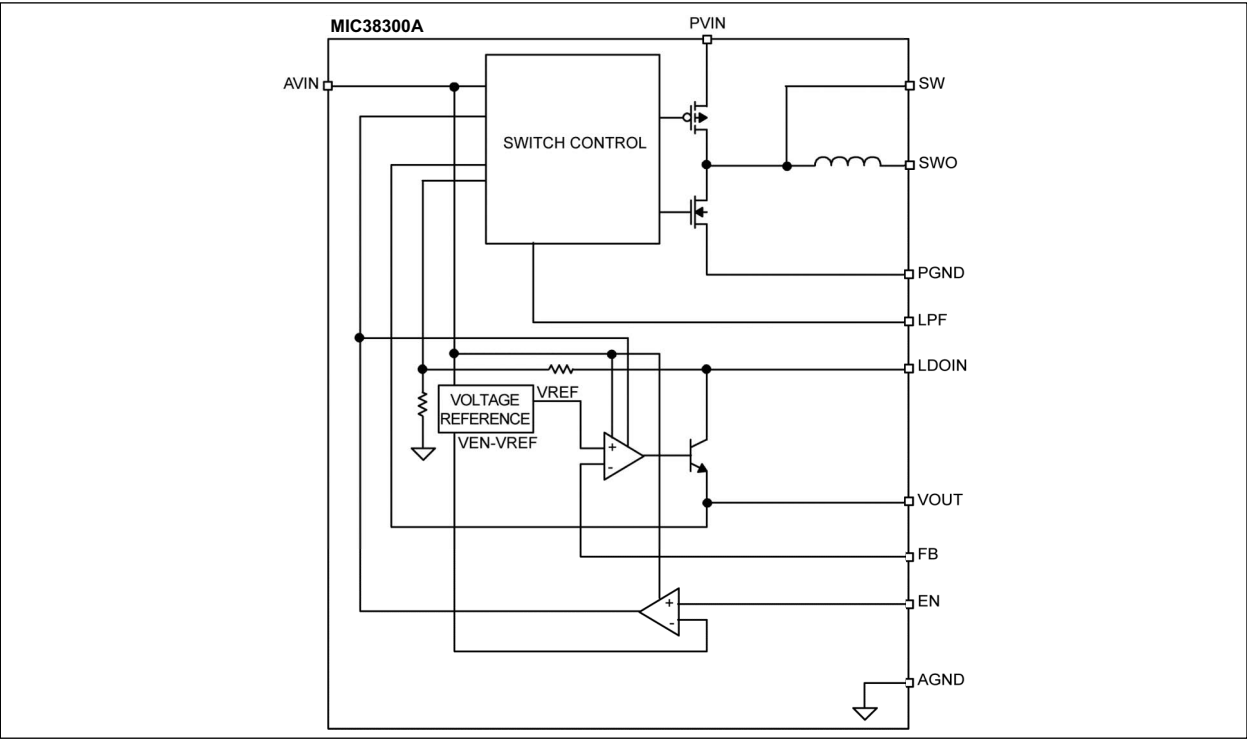


MIC38300A

Package Type



Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage (V_{IN})	+6V
Output Switch Voltage (V_{SW})	+6V
LDO Output Voltage (V_{OUT})	+6V
Logic Input Voltage (V_{EN})	-0.3V to V_{IN}
Power Dissipation (Note 1)	Internally Limited
ESD Rating (Note 2)	1 kV

Operating Ratings ‡

Supply Voltage (V_{IN})	+3.0V to +5.5V
Enable Input Voltage (V_{EN})	0V to V_{IN}

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

‡ **Notice:** The device is not guaranteed to function outside its operating ratings.

Note 1: The maximum allowable power dissipation of any T_A (ambient temperature) is $P_{D(MAX)} = (T_{J(MAX)} - T_A)/\theta_{JA}$. Exceeding the maximum allowable power dissipation will result in excessive die temperature, and the regulator will go into thermal shutdown.

2: Devices are ESD sensitive. Handling precautions recommended. Human body model, 1.5 k Ω in series with 100 pF.

ELECTRICAL CHARACTERISTICS

$T_A = +25^\circ\text{C}$ with $V_{IN} = V_{EN} = 5\text{V}$; $I_{OUT} = 10\text{ mA}$, $V_{OUT} = 1.8\text{V}$. **Bold** values valid for $-40^\circ\text{C} \leq T_J \leq +125^\circ\text{C}$, unless noted. [Note 1](#)

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Supply Voltage Range (AV_{IN} , PV_{IN})	—	3.0	—	5.5	V	—
Undervoltage Lockout Threshold	—	—	2.85	—	V	Turn-on
UVLO Hysteresis	—	—	100	—	mV	—
Quiescent Current	I_Q	—	1	—	mA	$I_{OUT} = 0\text{A}$, Not switching, open loop
Turn-On Time	t_{ON}	—	200	500	μs	V_{OUT} to 95% of nominal
Shutdown Current	I_{SHDN}	—	30	50	μA	$V_{EN} = 0\text{V}$
Feedback Voltage	V_{FB}	0.975	1	1.025	V	$\pm 2.5\%$
Feedback Current	I_{FB}	—	5	—	nA	—
Dropout Voltage ($V_{IN} - V_{OUT}$)	V_{DO}	—	0.85	1.2	V	$I_{LOAD} = 3\text{A}$, $V_{OUT} = 3\text{V}$
Current Limit	I_{LIM}	—	5	—	A	$V_{FB} = 0.9 \times V_{NOM}$
Output Voltage Load Regulation	—	—	0.3	1	%	$V_{OUT} = 1.8\text{V}$, 10 mA to 3A
Output Voltage Line Regulation	—	—	0.35	0.5	%/V	$V_{OUT} = 1.8\text{V}$, V_{IN} from 3.0V to 5.5V
Output Ripple	—	—	2	—	mV	$I_{LOAD} = 1.5\text{A}$, $C_{OUTLDO} = 20\text{ }\mu\text{F}$, $C_{OUTSW} = 20\text{ }\mu\text{F}$, $R_{LFP} = 75\text{ k}\Omega$
Overtemperature Shutdown	—	—	150	—	$^\circ\text{C}$	—
Overtemperature Shutdown Hysteresis	—	—	15	—	$^\circ\text{C}$	—

MIC38300A

ELECTRICAL CHARACTERISTICS (CONTINUED)

$T_A = +25^{\circ}\text{C}$ with $V_{IN} = V_{EN} = 5\text{V}$; $I_{OUT} = 10\text{ mA}$, $V_{OUT} = 1.8\text{V}$. **Bold** values valid for $-40^{\circ}\text{C} \leq T_J \leq +125^{\circ}\text{C}$, unless noted. [Note 1](#)

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Enable Input (Note 2)						
Enable Input Threshold	—	0.90	1	1.1	V	Regulator enable
Enable Hysteresis	—	20	100	200	mV	—
Enable Input Current	—	—	0.03	1	μA	—

Note 1: Specification for packaged product only.

2: Enable pin should not be left open.

TEMPERATURE SPECIFICATIONS

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Storage Temperature Range	T_S	-65	—	+150	$^{\circ}\text{C}$	—
Junction Temperature Range	T_J	-40	—	+125	$^{\circ}\text{C}$	—
Package Thermal Resistances						
Thermal Resistance, LQFN 28-Ld	θ_{JA}	—	24	—	$^{\circ}\text{C/W}$	—

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

$V_{IN} = 3.3V$, $V_{OUT} = 1.8V$, $C_{OUT} = 20 \mu F$, $R_{LPF} = 75 k\Omega$, $I_{OUT} = 100 mA$, unless noted.

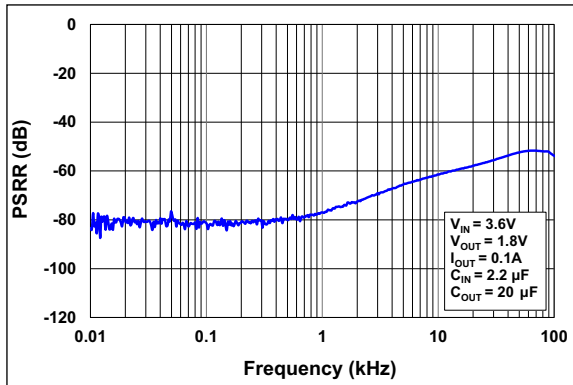


FIGURE 2-1: Power Supply Ripple Rejection.

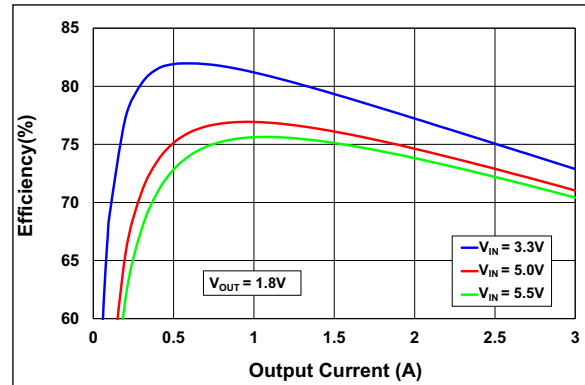


FIGURE 2-4: Efficiency ($V_{OUT} = 1.8V$).

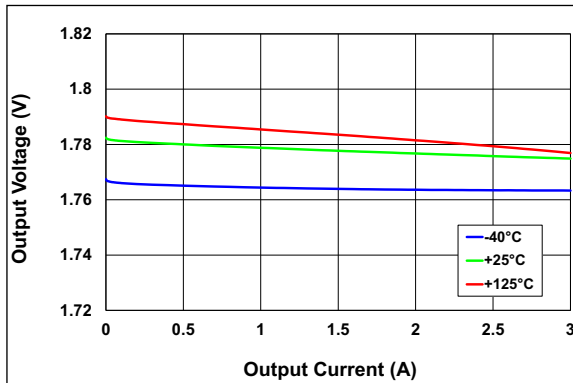


FIGURE 2-2: Load Regulation.

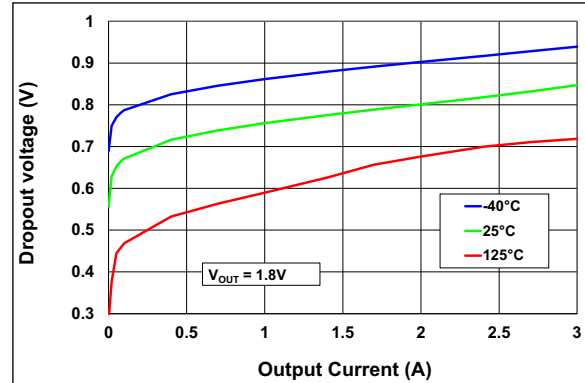


FIGURE 2-5: Dropout Voltage.

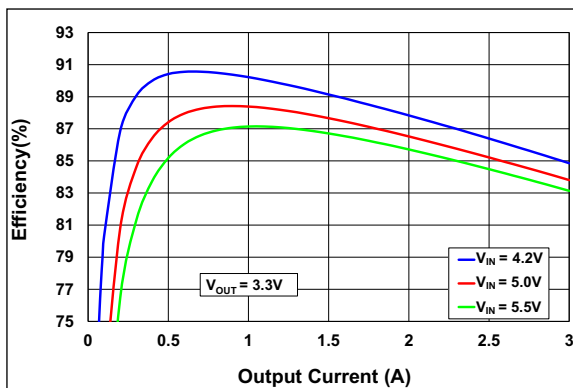


FIGURE 2-3: Efficiency ($V_{OUT} = 3.3V$).

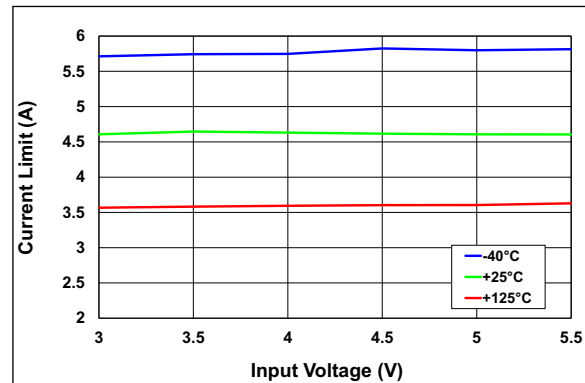


FIGURE 2-6: Current Limit.

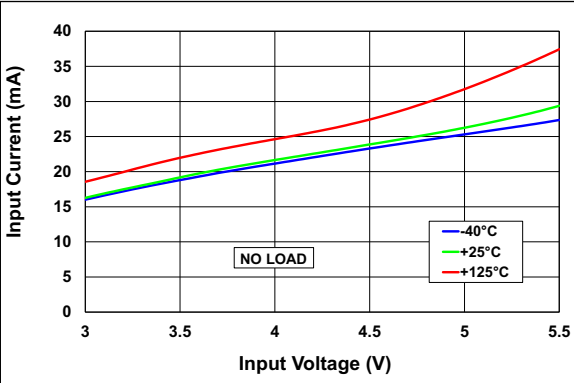


FIGURE 2-7: No-Load Input Current.

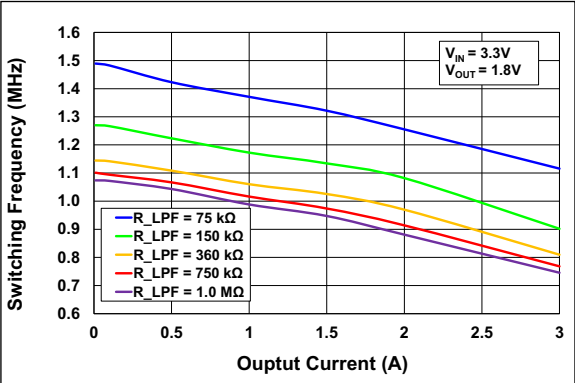


FIGURE 2-10: Switching Frequency ($V_{IN} = 3.3V$, $V_{OUT} = 1.8V$).

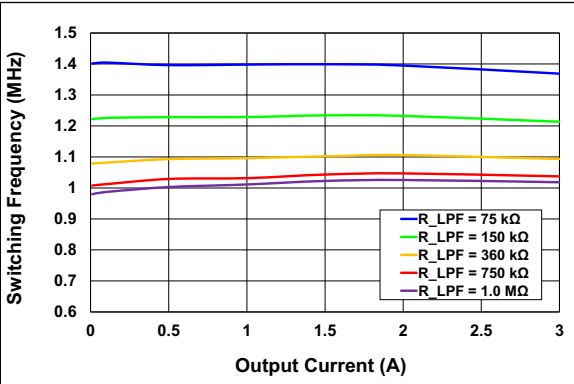


FIGURE 2-8: Switching Frequency ($V_{IN} = 3.3V$, $V_{OUT} = 1.0V$).

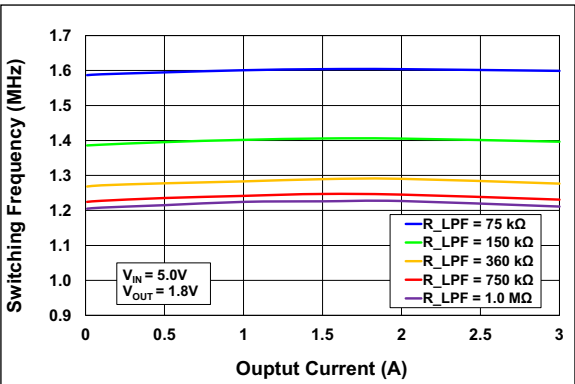


FIGURE 2-11: Switching Frequency ($V_{IN} = 5.0V$, $V_{OUT} = 1.8V$).

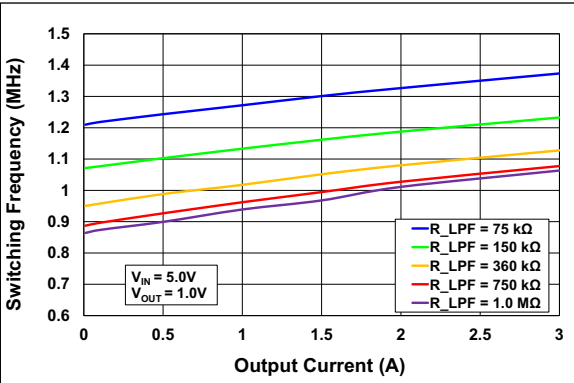


FIGURE 2-9: Switching Frequency ($V_{IN} = 5.0V$, $V_{OUT} = 1.0V$).

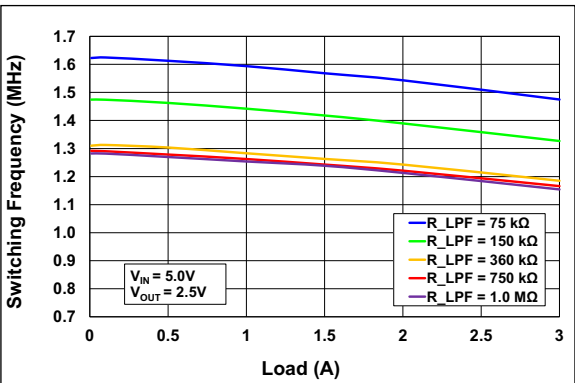


FIGURE 2-12: Switching Frequency ($V_{IN} = 5.0V$, $V_{OUT} = 2.5V$).

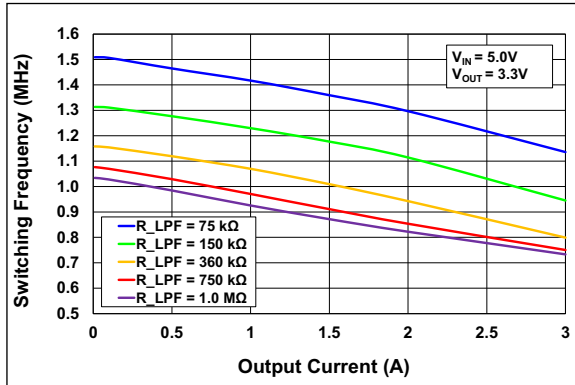


FIGURE 2-13: Switching Frequency
($V_{IN} = 5.0V$, $V_{OUT} = 3.3V$).

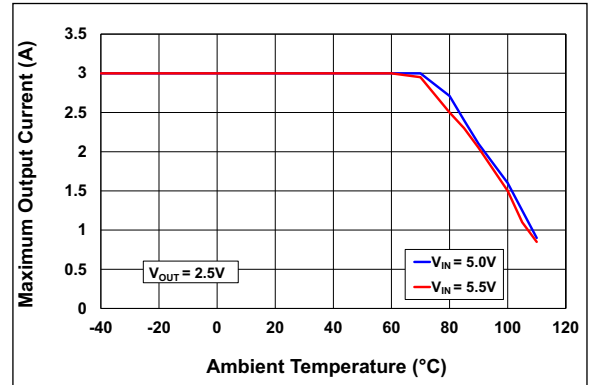


FIGURE 2-16: Current Derating
($V_{OUT} = 2.5V$).

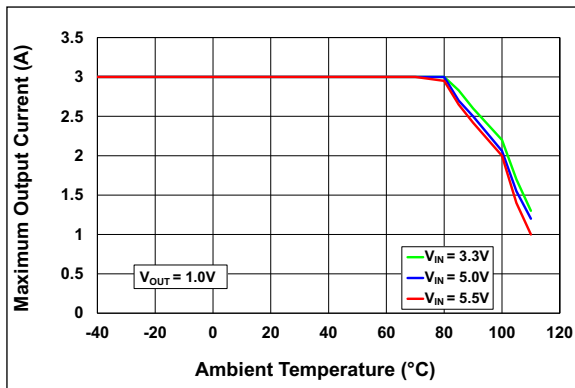


FIGURE 2-14: Current Derating
($V_{OUT} = 1.0V$).

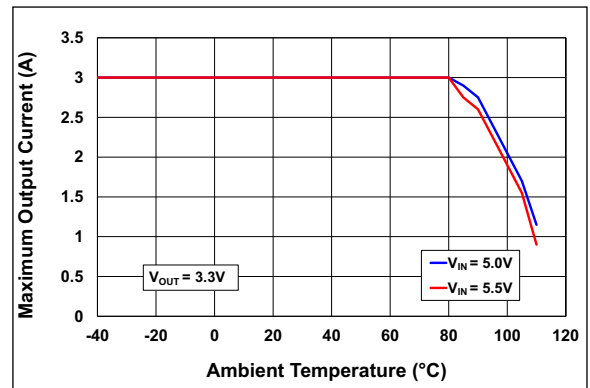


FIGURE 2-17: Current Derating
($V_{OUT} = 3.3V$).

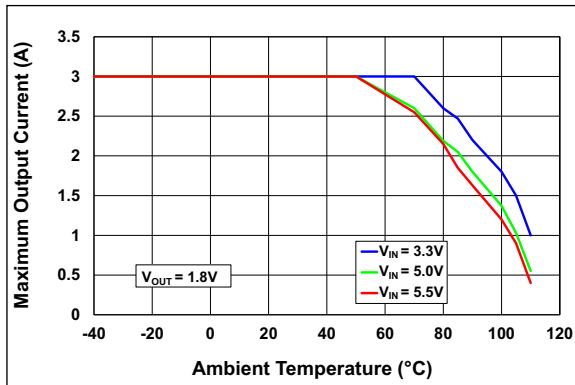


FIGURE 2-15: Current Derating
($V_{OUT} = 1.8V$).

Note: For Figure 2-14 through Figure 2-17, the following condition applies: Tested on Microchip Evaluation Board in thermal chamber, with approximately 20 to 30 LFM airflow. Case temperature is limited to 120°C.

MIC38300A

$V_{IN} = 3.3V$, $V_{OUT} = 1.8V$, $C_{OUT} = 10\ \mu F$, $R_{LPF} = 75\ k\Omega$, $I_{OUT} = 100\ mA$, unless noted.

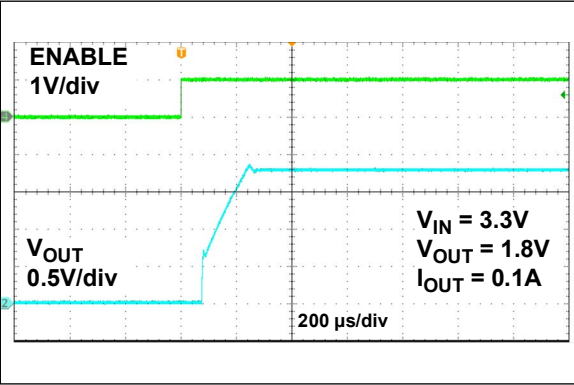


FIGURE 2-18: Start-Up from Enable.

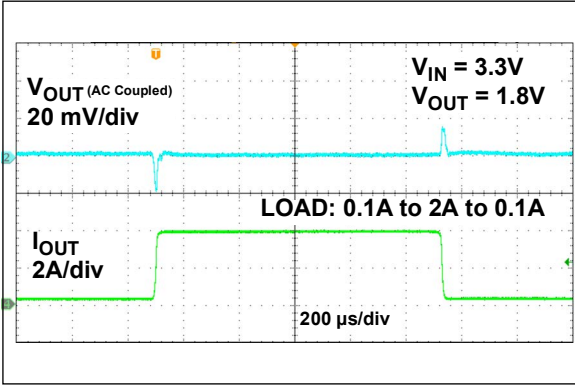


FIGURE 2-20: Load Transient Response.

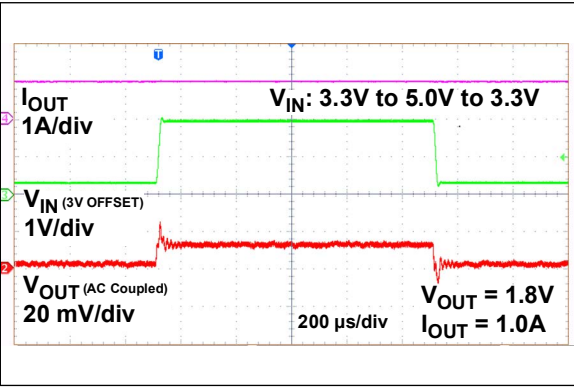


FIGURE 2-19: Line Transient Response.

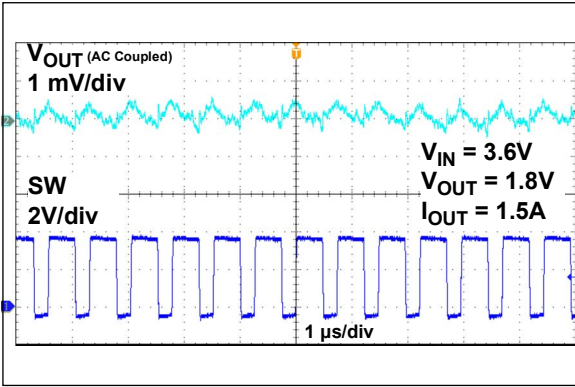


FIGURE 2-21: Output Voltage Ripple.

3.0 EMI PERFORMANCE

$V_{OUT} = 1.8V$, $I_{OUT} = 1.2A$.

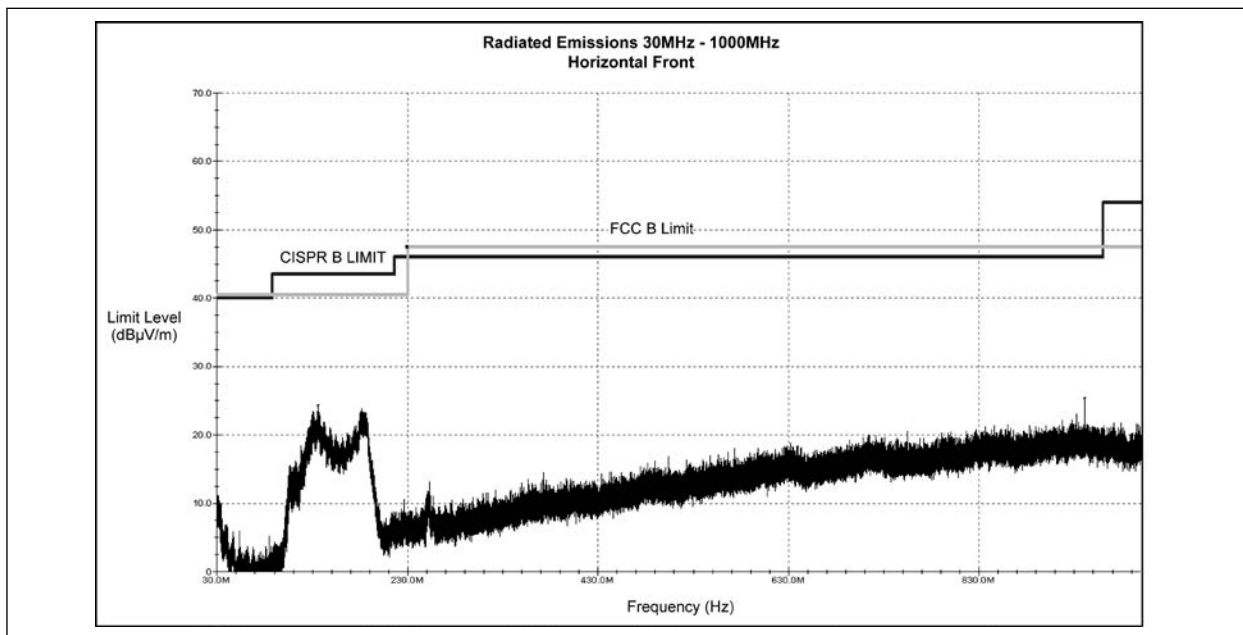


FIGURE 3-1: EMI Test: Horizontal Front.

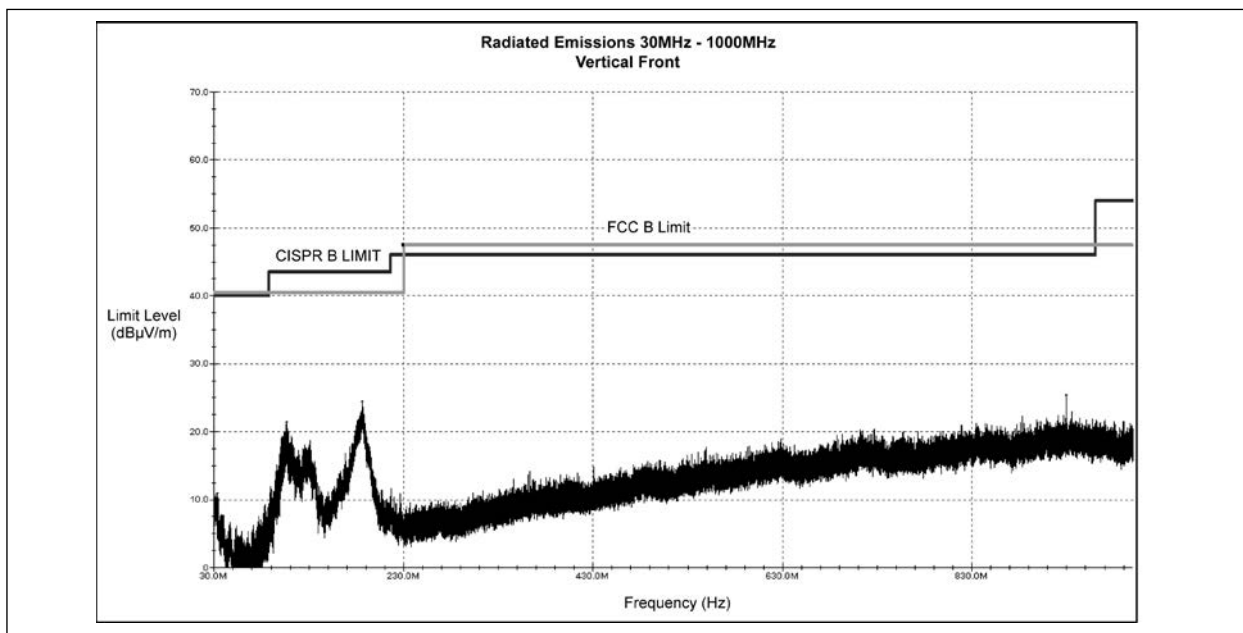


FIGURE 3-2: EMI Test: Vertical Front.

Additional components to MIC38150 Evaluation Board (Performance similar to MIC38300A):

1. Input Ferrite Bead Inductor. Part number: BLM21AG102SN1D.
2. 0.1 μF and 0.01 μF ceramic bypass capacitors on PVIN, SWO, and LDOOUT pins.

4.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 4-1](#).

TABLE 4-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1, 2, 3, 4, 5	SWO	Switch (Output): This is the output of the PFM Switcher.
6, 23, 24, 25, 26, 27, 28	SW	Switch Node: Attach external resistor from LPF to increase hysteretic frequency.
7, 22	ePAD	Exposed heat-sink pad. Connect externally to PGND.
8	AVIN	Analog Supply Voltage: Supply for the analog control circuitry. Requires bypass capacitor to ground. Nominal bypass capacitor is 1 μ F.
9	LPF	Low Pass Filter: Attach external resistor from SW to increase hysteretic frequency. Use a minimum value of 75 k Ω to maintain converter stability.
10	AGND	Analog Ground.
11	FB	Feedback: Input to the error amplifier. Connect to the external resistor divider network to set the output voltage.
12, 13	LDOOUT	LDO Output: Output of voltage regulator. Place capacitor to ground to bypass the output voltage. Nominal bypass capacitor is 10 μ F.
14, 15	LDOIN	LDO Input: Connect to SW output. Requires a bypass capacitor to ground. Nominal bypass capacitor is 10 μ F.
16, 17	PVIN	Input Supply Voltage (Input): Requires bypass capacitor to GND. Nominal bypass capacitor is 10 μ F.
18	EN	Enable (Input): Logic low will shut down the device, reducing the quiescent current to less than 50 μ A. This pin can also be used as an undervoltage lockout function by connecting a resistor divider from EN/UVLO pin to VIN and GND. It should be not left open.
19, 20, 21	PGND	Power Ground.

5.0 APPLICATION INFORMATION

5.1 Enable Input

The MIC38300A features a TTL/CMOS compatible positive logic enable input for on/off control of the device. High enables the regulator, while low disables the regulator. In shutdown, the regulator consumes very little current (only a few microamperes of leakage). For simple applications, the enable (EN) can be connected to VIN (IN).

5.2 Input Capacitor

PVIN provides power to the MOSFETs for the switch mode regulator section and the gate drivers. Due to the high switching speeds, a 10 μ F capacitor is recommended close to PVIN and the power ground (PGND) pin for bypassing.

Analog VIN (AVIN) provides power to the analog supply circuitry. Careful layout should be considered to ensure high-frequency switching noise caused by PVIN is reduced before reaching AVIN. A 1 μ F capacitor as close to AVIN as possible is recommended.

5.3 Output Capacitor

The MIC38300A requires an output capacitor for stable operation. As a μ Cap LDO, the MIC38300A can operate with ceramic output capacitors of 10 μ F or greater. Values of greater than 10 μ F improve transient response and noise reduction at high frequency. X7R/X5R dielectric-type ceramic capacitors are recommended because of their superior temperature performance. X7R-type capacitors change capacitance by 15% over their operating temperature range and are the most stable type of ceramic capacitors. Larger output capacitances can be achieved by placing tantalum or aluminum electrolytics in parallel with the ceramic capacitor. For example, a 100 μ F electrolytic in parallel with a 10 μ F ceramic can provide the transient and high frequency noise performance of a 100 μ F ceramic at a significantly lower cost. Specific undershoot/overshoot performance will depend on both the values and ESR/ESL of the capacitors.

For less than 5 mV noise performance at higher current loads, 20 μ F capacitors are recommended at LDOIN and LDOOUT.

5.4 Low Pass Filter Pin

The MIC38300A features a Low Pass Filter (LPF) pin for adjusting the switcher frequency. By tuning the frequency, the user can further improve output ripple without losing efficiency. Adjusting the frequency is accomplished by connecting a resistor between the LPF and SW pins. A small value resistor would increase the frequency while a larger value resistor

decreases the frequency. Recommended R_{LPF} value is 75 k Ω . Please see the [Typical Performance Curves](#) section for more details.

5.5 Adjustable Regulator Design

The adjustable MIC38300A output voltage can be programmed from 1V to 5.0V using a resistor divider from output to the FB pin. Resistors can be quite large, up to 100 k Ω because of the very high input impedance and low bias current of the sense amplifier. For large value resistors (>50 k Ω) R1 should be bypassed by a small capacitor ($C_{FF} = 0.1 \mu$ F bypass capacitor) to avoid instability due to phase lag at the ADJ/SNS input.

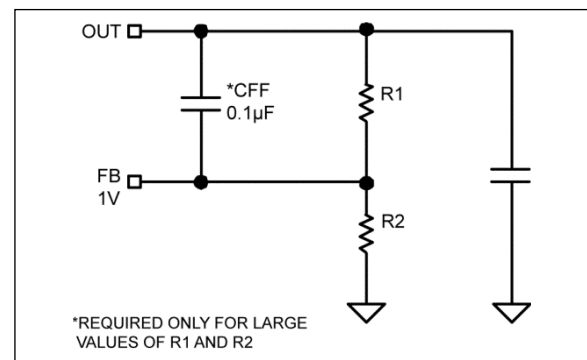


FIGURE 5-1: Adjustable Regulator with Resistors.

The output resistor divider values are calculated by Equation 5-1.

EQUATION 5-1:

$$V_{OUT} = 1V \times \left(\frac{R1}{R2} + 1 \right)$$

5.6 Efficiency Considerations

Efficiency is defined as the amount of useful output power, divided by the amount of power supplied.

EQUATION 5-2:

$$\text{Efficiency \%} = \left(\frac{V_{OUT} \times I_{OUT}}{V_{IN} \times I_{IN}} \right) \times 100$$

Maintaining high efficiency serves two purposes. It reduces power dissipation in the power supply, reducing the need for heat sinks and thermal design considerations and it reduces consumption of current for battery-powered applications. Reduced current draw from a battery increases the devices operating time and is critical in handheld devices.

There are two types of losses in switching converters: DC losses and switching losses. DC losses are simply the power dissipation of I^2R . Power is dissipated in the high-side switch during the on cycle. Power loss is equal to the high-side MOSFET $R_{DS(ON)}$ multiplied by the switch current. During the off cycle, the low-side N-channel MOSFET conducts, also dissipating power. Device operating current also reduces efficiency. The product of the quiescent (operating) current and the supply voltage is another DC loss.

Over 100 mA, efficiency loss is dominated by MOSFET $R_{DS(ON)}$ and inductor losses. Higher input supply voltages will increase the gate-to-source threshold on the internal MOSFETs, reducing the internal $R_{DS(ON)}$. This improves efficiency by reducing DC losses in the device. All but the inductor losses are inherent to the device. In which case, inductor selection becomes increasingly critical in efficiency calculations. As the inductors are reduced in size, the DC resistance (DCR) can become quite significant. The DCR losses can be calculated as in Equation 5-3.

EQUATION 5-3:

$$L_P_D = I_{OUT}^2 \times DCR$$

From that, the loss in efficiency due to inductor resistance can be calculated as in Equation 5-4:

EQUATION 5-4:

$$Eff_Loss = \left[1 - \left(\frac{V_{OUT} \times I_{OUT}}{V_{OUT} \times I_{OUT} + L_P_D} \right) \right] \times 100$$

Efficiency loss due to DCR is minimal at light loads and gains significance as the load is increased. Inductor selection becomes a trade-off between efficiency and size in this case.

5.7 Current-Sharing Circuit

Figure 5-2 allows two MIC38300A regulators to share the load current equally. Regulator1 senses the output voltage at the load, on the other side of a current sense resistor. As the load changes, a voltage equal to the output voltage, plus the load current times the sense resistor, is developed at the V_{OUT} terminal of Regulator1. The op-amp (MIC7300) inverting pin senses this voltage and compares it to the voltage on the V_{OUT} terminal of Regulator2.

If the current through the current sense of Regulator2 is less than the current through the current sense of Regulator1, the inverting pin will be at a higher voltage than the non-inverting pin and the op-amp will drive the FB of Regulator2 low. The low voltage sensed on Regulator2's FB pin will drive the output up until the output voltage of Regulator2 matches the output voltage of Regulator1. Because V_{OUT} will remain constant and both Regulators' V_{OUT} terminals and sense resistances are matched, the output currents will be shared equally.

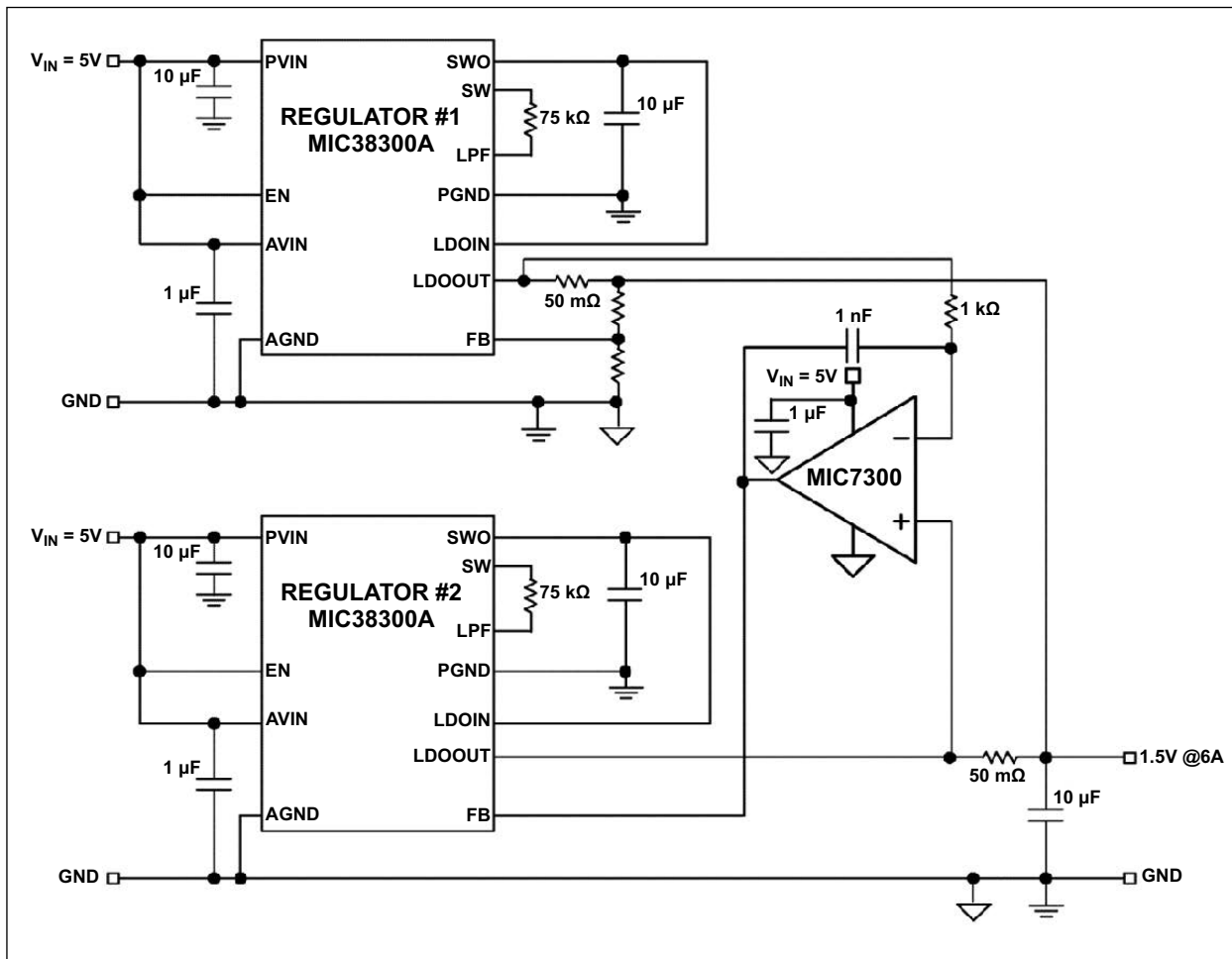
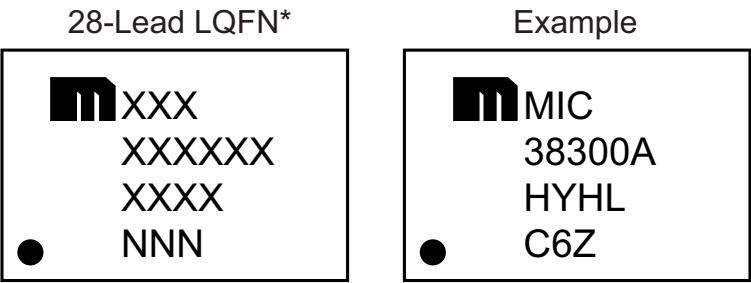


FIGURE 5-2: Current-Sharing Circuit for 6A Output.

MIC38300A

6.0 PACKAGING INFORMATION

6.1 Package Marking Information

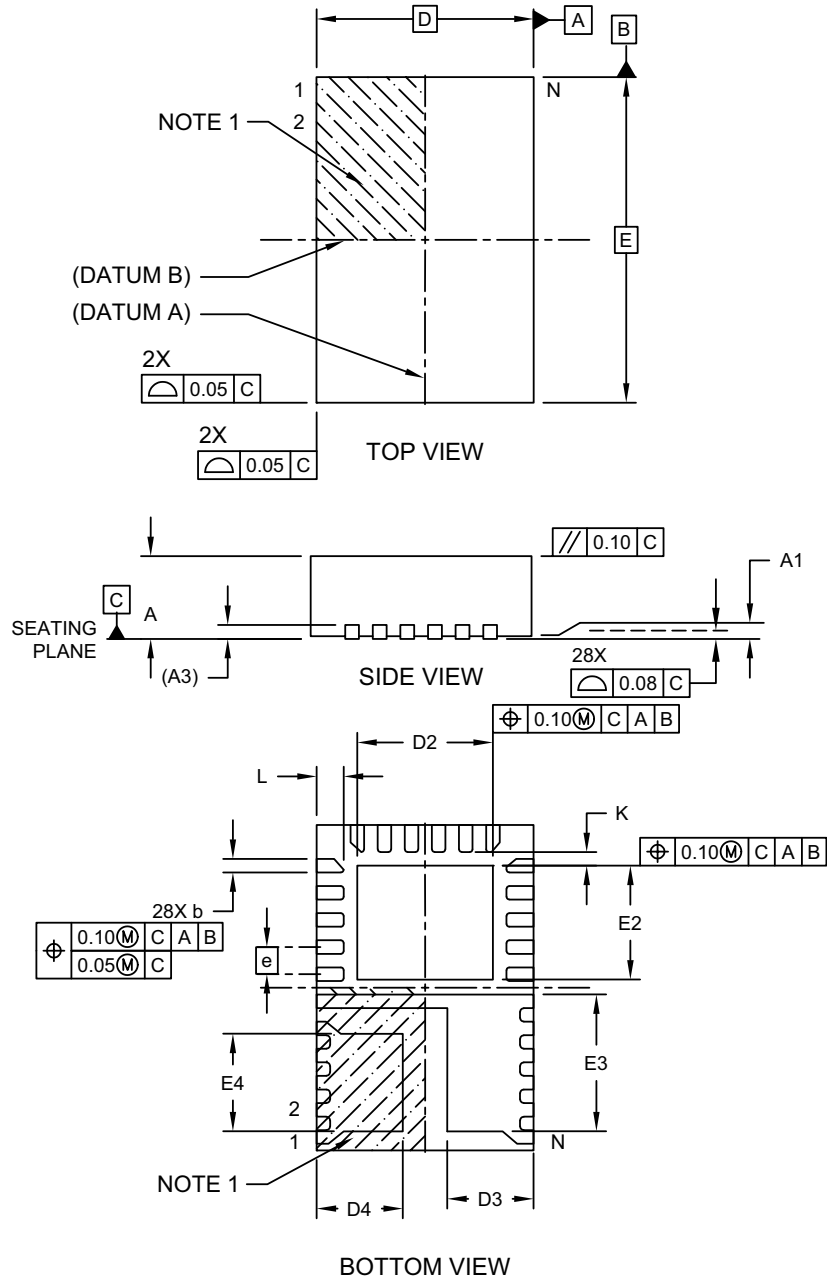


Legend:	XX...X	Product code or customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
	•, ▲, ▼	Pin one index is identified by a dot, delta up, or delta down (triangle mark).
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information. Package may or may not include the corporate logo.	
	Underbar (_) and/or Overbar (¯) symbol may not be to scale.	

Note: If the full seven-character YYWWNNN code cannot fit on the package, the following truncated codes are used based on the available marking space:
6 Characters = YWWNNN; 5 Characters = WWNNN; 4 Characters = WNNN; 3 Characters = NNN;
2 Characters = NN; 1 Character = N

28-Lead Thick Plastic Quad Flat, No Lead Package (LYA) - 4x6 mm Body [LQFN] With Multiple Fused Exposed Pads

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

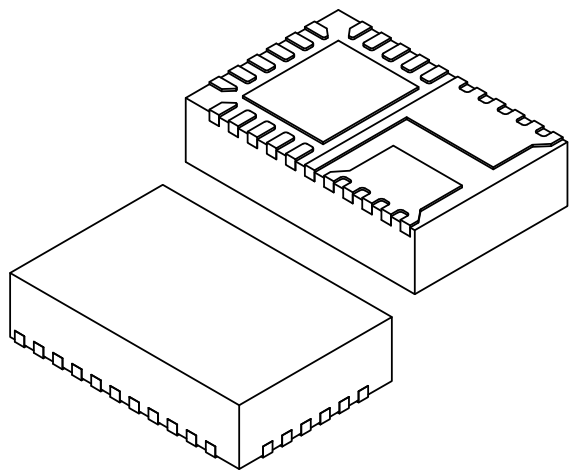


Microchip Technology Drawing C04-1294 Rev A Sheet 1 of 2

MIC38300A

28-Lead Thick Plastic Quad Flat, No Lead Package (LYA) - 4x6 mm Body [LQFN] With Multiple Fused Exposed Pads

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



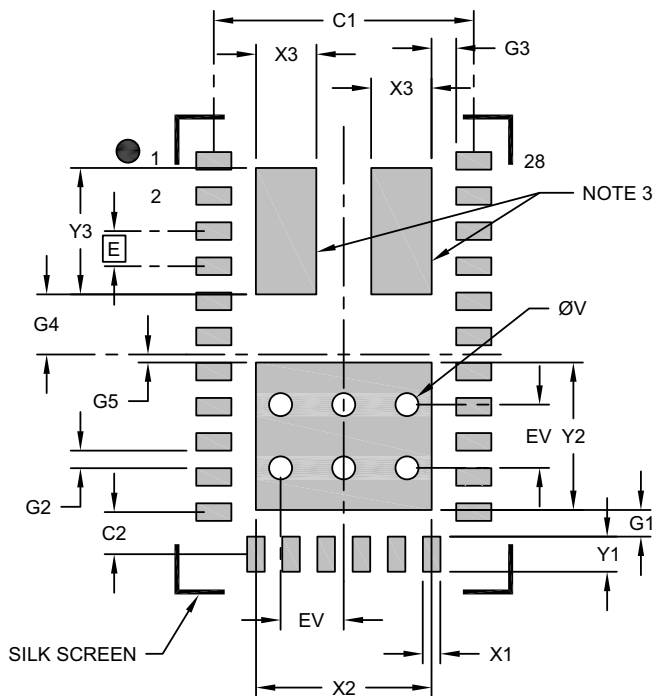
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	28		
Pitch	e	0.50 BSC		
Overall Height	A	1.45	1.50	1.55
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3	0.203 REF		
Overall Length	D	4.00 BSC		
Exposed Pad Length	D2	2.45	2.50	2.55
Exposed Pad Length	D3	1.57	1.62	1.67
Exposed Pad Length	D4	1.57	1.62	1.67
Overall Width	E	6.00 BSC		
Exposed Pad Width	E2	2.05	2.10	2.15
Exposed Pad Width	E3	2.47	2.52	2.57
Exposed Pad Width	E4	1.75	1.80	1.85
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.45	0.50	0.55

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

28-Lead Thick Plastic Quad Flat, No Lead Package (LYA) - 4x6 mm Body [LQFN] With Multiple Fused Exposed Pads

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Center Pad Width	X2			2.52
Center Pad Length	Y2			2.10
Center Pad Width	X3			0.86
Center Pad Length (X2)	Y3			1.80
Contact Pad Spacing	C1		3.70	
Contact Pad Spacing	C2		0.60	
Contact Pad Width (X28)	X1			0.27
Contact Pad Length (X28)	Y1			0.52
Contact Pad to Center Pad (X6)	G1	0.38		
Contact Pad to Contact Pad (X25)	G2	0.25		
Contact Pad to Contact Pad (X2)	G3	0.35		
Package Center to Center Pad (X2)	G4		0.86	
Package Center to Center Pad	G5		0.12	
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		0.90	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process
3. These center pads have different electrical potentials. DO NOT CONNECT TO GROUND.

Microchip Technology Drawing C04-3294 Rev A

MIC38300A

APPENDIX A: REVISION HISTORY

Revision B (April 2024)

- Updated [Typical Performance Curves](#) section to better describe the device.
- Updated [Figure 5-2](#) to improve clarity.

Revision A (November 2023)

- Initial release of MIC38300A as Microchip data sheet DS20006831A.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>	<u>X</u>	<u>X</u>	<u>XX</u>	<u>-XX</u>
Device	Output Current	Temperature Range	Package	Media Type
Device:	MIC38300A:	3A High Efficiency Low Dropout Regulator		
Output Current:	H	= 3A		
Temperature Range:	Y	= -40°C to +125°C		
Package:	HL	= 28-Lead LQFN		
Media Type:	TR	= 1,000/Reel		

Examples:

a) MIC38300AHYHL-TR: MIC38300A, 3A Output Current, -40°C to +125°C Temp. Range, 28-Lead LQFN, 1,000/Reel

Note: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

MIC38300A

NOTES:

Note the following details of the code protection feature on Microchip products:

- Microchip products meet the specifications contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
- Microchip values and aggressively protects its intellectual property rights. Attempts to breach the code protection features of Microchip product is strictly prohibited and may violate the Digital Millennium Copyright Act.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of its code. Code protection does not mean that we are guaranteeing the product is "unbreakable" Code protection is constantly evolving. Microchip is committed to continuously improving the code protection features of our products.

This publication and the information herein may be used only with Microchip products, including to design, test, and integrate Microchip products with your application. Use of this information in any other manner violates these terms. Information regarding device applications is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. Contact your local Microchip sales office for additional support or, obtain additional support at <https://www.microchip.com/en-us/support/design-help/client-support-services>.

THIS INFORMATION IS PROVIDED BY MICROCHIP "AS IS". MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION INCLUDING BUT NOT LIMITED TO ANY IMPLIED WARRANTIES OF NON-INFRINGEMENT, MERCHANTABILITY, AND FITNESS FOR A PARTICULAR PURPOSE, OR WARRANTIES RELATED TO ITS CONDITION, QUALITY, OR PERFORMANCE.

IN NO EVENT WILL MICROCHIP BE LIABLE FOR ANY INDIRECT, SPECIAL, PUNITIVE, INCIDENTAL, OR CONSEQUENTIAL LOSS, DAMAGE, COST, OR EXPENSE OF ANY KIND WHATSOEVER RELATED TO THE INFORMATION OR ITS USE, HOWEVER CAUSED, EVEN IF MICROCHIP HAS BEEN ADVISED OF THE POSSIBILITY OR THE DAMAGES ARE FORESEEABLE. TO THE FULLEST EXTENT ALLOWED BY LAW, MICROCHIP'S TOTAL LIABILITY ON ALL CLAIMS IN ANY WAY RELATED TO THE INFORMATION OR ITS USE WILL NOT EXCEED THE AMOUNT OF FEES, IF ANY, THAT YOU HAVE PAID DIRECTLY TO MICROCHIP FOR THE INFORMATION.

Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

For information regarding Microchip's Quality Management Systems, please visit www.microchip.com/quality.

Trademarks

The Microchip name and logo, the Microchip logo, Adaptec, AVR, AVR logo, AVR Freaks, BesTime, BitCloud, CryptoMemory, CryptoRF, dsPIC, flexPWR, HELDO, IGLOO, JukeBlox, KeeLoq, Klear, LANCheck, LinkMD, maXStylus, maXTouch, MediaLB, megaAVR, Microsemi, Microsemi logo, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, PolarFire, Prochip Designer, QTouch, SAM-BA, SenGenuity, SpyNIC, SST, SST Logo, SuperFlash, Symmetricon, SyncServer, Tachyon, TimeSource, tinyAVR, UNI/O, Vectron, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

AgileSwitch, ClockWorks, The Embedded Control Solutions Company, EtherSynch, Flashtec, Hyper Speed Control, HyperLight Load, Libero, motorBench, mTouch, Powermite 3, Precision Edge, ProASIC, ProASIC Plus, ProASIC Plus logo, Quiet-Wire, SmartFusion, SyncWorld, TimeCesium, TimeHub, TimePictra, TimeProvider, and ZL are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, Augmented Switching, BlueSky, BodyCom, Clockstudio, CodeGuard, CryptoAuthentication, CryptoAutomotive, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, Espresso T1S, EtherGREEN, EyeOpen, GridTime, IdealBridge, IGaT, In-Circuit Serial Programming, ICSP, INICnet, Intelligent Paralleling, IntelliMOS, Inter-Chip Connectivity, JitterBlocker, Knob-on-Display, MarginLink, maxCrypto, maxView, memBrain, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mSiC, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, Power MOS IV, Power MOS 7, PowerSmart, PureSilicon, QMatrix, REAL ICE, Ripple Blocker, RTAX, RTG4, SAM-ICE, Serial Quad I/O, simpleMAP, SimpliPHY, SmartBuffer, SmartHLS, SMART-I.S., storClad, SQL, SuperSwitcher, SuperSwitcher II, Switchtec, SynchroPHY, Total Endurance, Trusted Time, TSHARC, Turing, USBCheck, VariSense, VectorBlox, VeriPHY, ViewSpan, WiperLock, XpressConnect, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

The Adaptec logo, Frequency on Demand, Silicon Storage Technology, and Symmcom are registered trademarks of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2023 - 2024, Microchip Technology Incorporated and its subsidiaries.

All Rights Reserved.

ISBN: 978-1-6683-4357-9

Worldwide Sales and Service

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://www.microchip.com/support>
Web Address:
www.microchip.com

Atlanta
Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Austin, TX
Tel: 512-257-3370

Boston
Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago
Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Dallas
Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit
Novi, MI
Tel: 248-848-4000

Houston, TX
Tel: 281-894-5983

Indianapolis
Noblesville, IN
Tel: 317-773-8323
Fax: 317-773-5453
Tel: 317-536-2380

Los Angeles
Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608
Tel: 951-273-7800

Raleigh, NC
Tel: 919-844-7510

New York, NY
Tel: 631-435-6000

San Jose, CA
Tel: 408-735-9110
Tel: 408-436-4270

Canada - Toronto
Tel: 905-695-1980
Fax: 905-695-2078

ASIA/PACIFIC

Australia - Sydney
Tel: 61-2-9868-6733

China - Beijing
Tel: 86-10-8569-7000

China - Chengdu
Tel: 86-28-8665-5511

China - Chongqing
Tel: 86-23-8980-9588

China - Dongguan
Tel: 86-769-8702-9880

China - Guangzhou
Tel: 86-20-8755-8029

China - Hangzhou
Tel: 86-571-8792-8115

China - Hong Kong SAR
Tel: 852-2943-5100

China - Nanjing
Tel: 86-25-8473-2460

China - Qingdao
Tel: 86-532-8502-7355

China - Shanghai
Tel: 86-21-3326-8000

China - Shenyang
Tel: 86-24-2334-2829

China - Shenzhen
Tel: 86-755-8864-2200

China - Suzhou
Tel: 86-186-6233-1526

China - Wuhan
Tel: 86-27-5980-5300

China - Xian
Tel: 86-29-8833-7252

China - Xiamen
Tel: 86-592-2388138

China - Zhuhai
Tel: 86-756-3210040

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-3090-4444

India - New Delhi
Tel: 91-11-4160-8631

India - Pune
Tel: 91-20-4121-0141

Japan - Osaka
Tel: 81-6-6152-7160

Japan - Tokyo
Tel: 81-3-6880-3770

Korea - Daegu
Tel: 82-53-744-4301

Korea - Seoul
Tel: 82-2-554-7200

Malaysia - Kuala Lumpur
Tel: 60-3-7651-7906

Malaysia - Penang
Tel: 60-4-227-8870

Philippines - Manila
Tel: 63-2-634-9065

Singapore
Tel: 65-6334-8870

Taiwan - Hsin Chu
Tel: 886-3-577-8366

Taiwan - Kaohsiung
Tel: 886-7-213-7830

Taiwan - Taipei
Tel: 886-2-2508-8600

Thailand - Bangkok
Tel: 66-2-694-1351

Vietnam - Ho Chi Minh
Tel: 84-28-5448-2100

EUROPE

Austria - Wels
Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4485-5910
Fax: 45-4485-2829

Finland - Espoo
Tel: 358-9-4520-820

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Garching
Tel: 49-8931-9700

Germany - Haan
Tel: 49-2129-3766400

Germany - Heilbronn
Tel: 49-7131-72400

Germany - Karlsruhe
Tel: 49-721-625370

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Germany - Rosenheim
Tel: 49-8031-354-560

Israel - Ra'anana
Tel: 972-9-744-7705

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Italy - Padova
Tel: 39-049-7625286

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Norway - Trondheim
Tel: 47-7288-4388

Poland - Warsaw
Tel: 48-22-3325737

Romania - Bucharest
Tel: 40-21-407-87-50

Spain - Madrid
Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

Sweden - Gothenberg
Tel: 46-31-704-60-40

Sweden - Stockholm
Tel: 46-8-5090-4654

UK - Wokingham
Tel: 44-118-921-5800
Fax: 44-118-921-5820

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Microchip:](#)

[MIC38300AHYHL-TR](#)